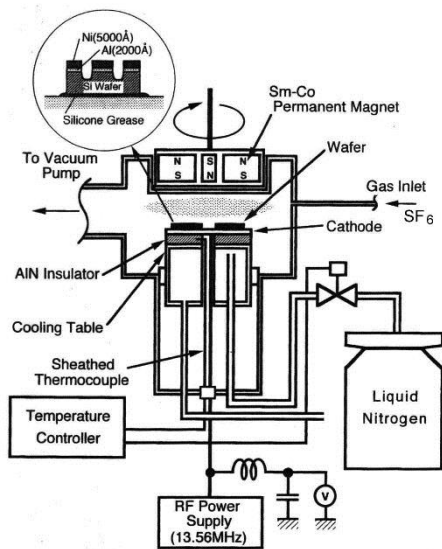
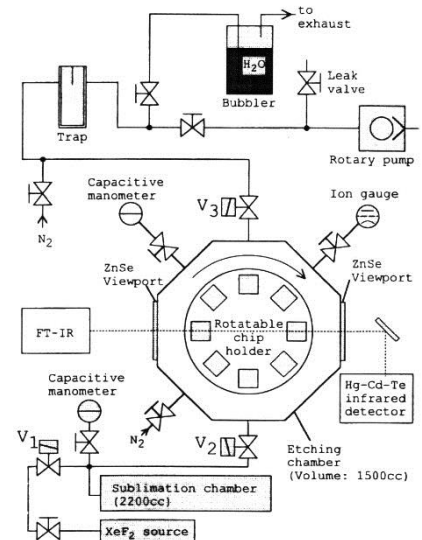
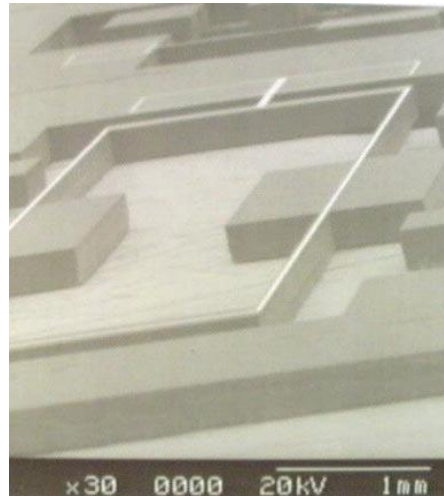


Micromachining and packaging (M.Esashi, S.Tanaka et.al)



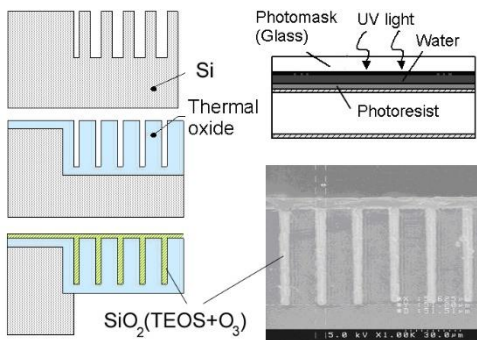
Deep RIE system and resonating gyro fabricated using it

(M.Takinami, Tech.Digest of the 11th Sensor Symp.(1992)15)



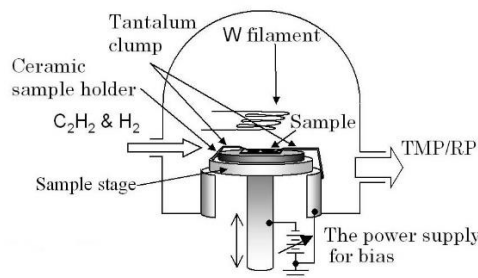
Si etching system using XeF_2

(R.Toda, Sensors & Actuators, A66(1998) 268)



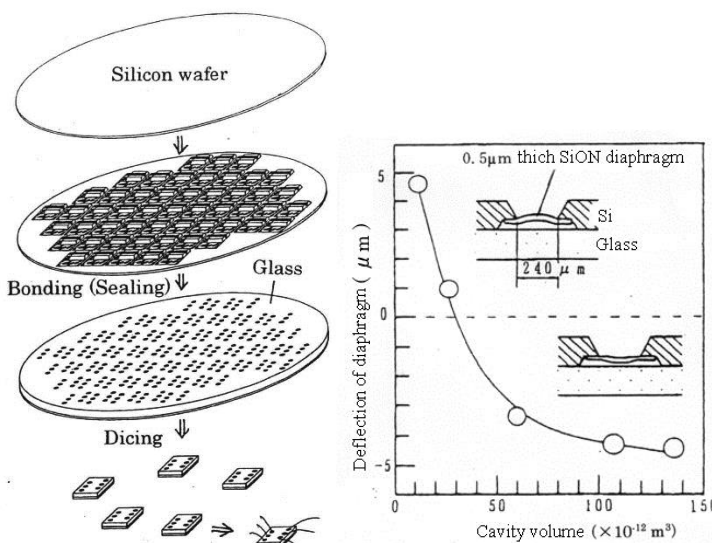
Water immersion contact lithography and trench refill.

(K.S.Chang, et.al, J.of Micromech. Microeng., 15 (2005) S171)

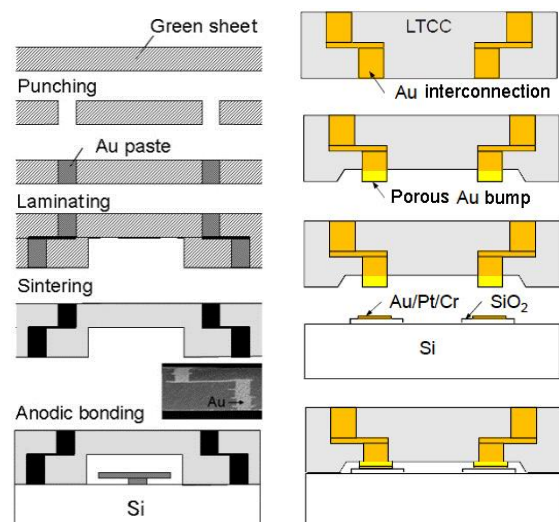


Hot filament CVD used for Carbon nanotube growth (or diamond film deposition).

(T.Ono et.al., Nanotechnology, 13 (2002) 62-64)



Wafer level packaging (WLP). O_2 generation during anodic bonding.



WLP using LTCC with electrical feedthrough.

(M.Esashi, J.of Micromech. and Microeng., 18 (2008) 073001) (S.Tanaka et.al., Technical Digest IEEE MEMS, (2012) 369)